Special Issue

Advances in Acoustic and Vibration MEMS

Message from the Guest Editors

MEMS technology has accelerated the development of traditional sensors toward miniaturization, low cost, low power consumption, and array integration. Acoustic and vibration sensors are high-demand devices, such as MEMS microphones, microspeakers, MEMS hydrophones, micromachined ultrasonic transducers, film bulk acoustic resonators, and microaccelerometers, which are widely applied in consumer electronics, industrial monitoring, marine safety, aerospace, and other fields. Innovative research on structures, simulation analysis, energy-conversion films, and fabrication techniques for acoustic and vibration sensors has the potential to significantly advance this field and broaden device applications. Accordingly, this Special Issue seeks to showcase research papers, communications, and review articles that focus on novel sensor structures, theoretical and numerical simulation, energy-conversion film, MEMS fabrication processes, and system integration of MEMS acoustic and vibration sensors, along with their application potential in healthcare, industrial inspection, marine safety, and aerospace.

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